

# **IPC/JPCA-4591**

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## **Requirements for Printed Electronics Functional Conductive Materials**

*A standard developed by IPC*

*Association Connecting Electronics Industries*



**JPCA**



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- Include a feedback system on use and problems for future improvement

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# Requirements for Printed Electronics Functional Conductive Materials

Developed by the Printed Electronics Functional Materials Subcommittee (D-63) of the Printed Electronics Committee (D-60) of IPC

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